

**AMENDMENTS TO THE CLAIMS****Claim 1 (previously amended)**

1. Hot-melt pressure-sensitive adhesive based one or more non-thermoplastic elastomers, comprising  
at least 100 parts by mass of one or more non-thermoplastic elastomers,  
from 1 to 100 parts by mass of one or more tackifying resins,  
from 1 to 100 parts by mass of one or more reactive phenolic resins, for the  
chemical/thermal crosslinking of the hot-melt pressure-sensitive adhesive, whose methylol  
content is from 1 to 20% by weight based on the reactive phenolic resin, and  
optionally from 1 to 100 parts by mass of accelerator substances.

**Claim 2 (previously added)**

2. Hot-melt pressure-sensitive adhesive according to Claim 1, wherein the non-thermoplastic  
elastomers are selected from the group consisting of natural rubbers, random-copolymerized  
styrene-butadiene rubbers (SBR), butadiene rubbers (BR), synthetic polyisoprenes (IR), butyl  
rubbers (IIR) and ethylene-vinyl acetate copolymers (EVA).

**Claim 3 (previously added)**

3. Hot-melt pressure-sensitive adhesive according to Claim 1, based on a polymer blend of one or more  
of the non-thermoplastic elastomers and one or more thermoplastic elastomers selected from the  
group consisting of polypropylenes, polyethylenes, metallocene-catalysed polyolefins, polyesters,  
polystyrenes and synthetic block copolymer rubbers.

**Claim 4 (previously added)**

4. Hot-melt pressure-sensitive adhesive according to Claim 1, wherein the crosslinking accelerator  
substances are selected from the group consisting of chloroprenes, metal oxides, organic acids or  
salts thereof, metal stearates and metal resinates.

**Claim 5 (previously added)**

5. Hot-melt pressure-sensitive adhesive according to Claim 1, wherein the reactive phenolic resins are  
halogenated and have a halogen content of from 1 to 20% by weight, based on the reactive  
phenolic resin.